
Financial Results Briefing for 1H FYE 12/2026

August 10, 2026



MEC COMPANY LTD.

Securities code: 4971

<https://www.mec-co.com/en/>

Note : This document has been translated from the Japanese original for reference purposes only. In the event of any discrepancy between this translated document and the Japanese original, the original shall prevail.

1H FYE12/2026 Key Factors

1

Sales: 12,594 million yen (YOY change: Up 34.2%)
Operating income: 4,135 million yen (YOY change: Up 69.4%)

2

Exchange rate impact (YOY change)
Sales: Up 777 million yen,
Operating income: Up 472 million yen.

3

Chemicals
Sales: 12,402 million yen (YOY change: Up 37.4%)
Shipments: 26,798 ton (YOY change: Up 21.9%)

4

Major products sales (YOY change)
EXE: Up 44.8% CZ: Up 37.1% V-Bond: Up 16.3% SF: Down 6.4%

Exchange Rates

Unit : yen

	Initial forecast	1H FYE12/2026	1H FYE12/2025	Q1 FYE12/2026
N T D	4.95	5.01	4.68	4.96
R M B	21.24	23.02	20.53	22.58
T H B	4.67	4.91	4.44	4.93
E U R	175.76	184.70	162.60	183.65
U S D	151.02	158.28	148.98	156.45

- Overseas subsidiaries are basically transactions denominated in local currency, and are affected by the yen / local currency rate when converting to yen in consolidated accounting.
- Our major foreign currencies are the Taiwan dollar (NTD) and the Chinese yuan (RMB). Both use the average rate during the period.

Exchange sensitivity (1H FY2026)

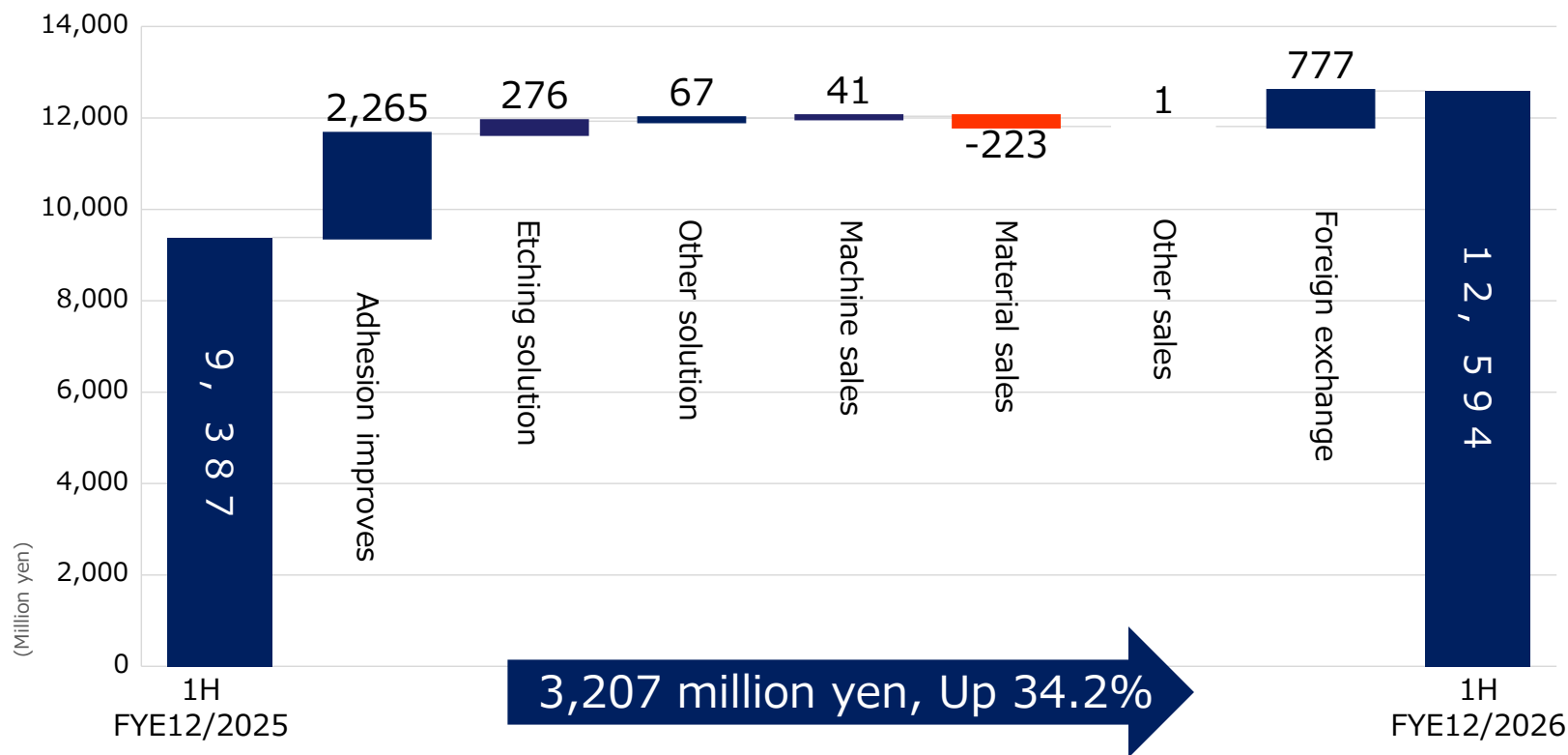
NTD: (Sale)	46 million yen
(Operating income)	35 million yen
RMB: (Sale)	17 million yen
(Operating income)	11 million yen

1H FYE12/2026 Results

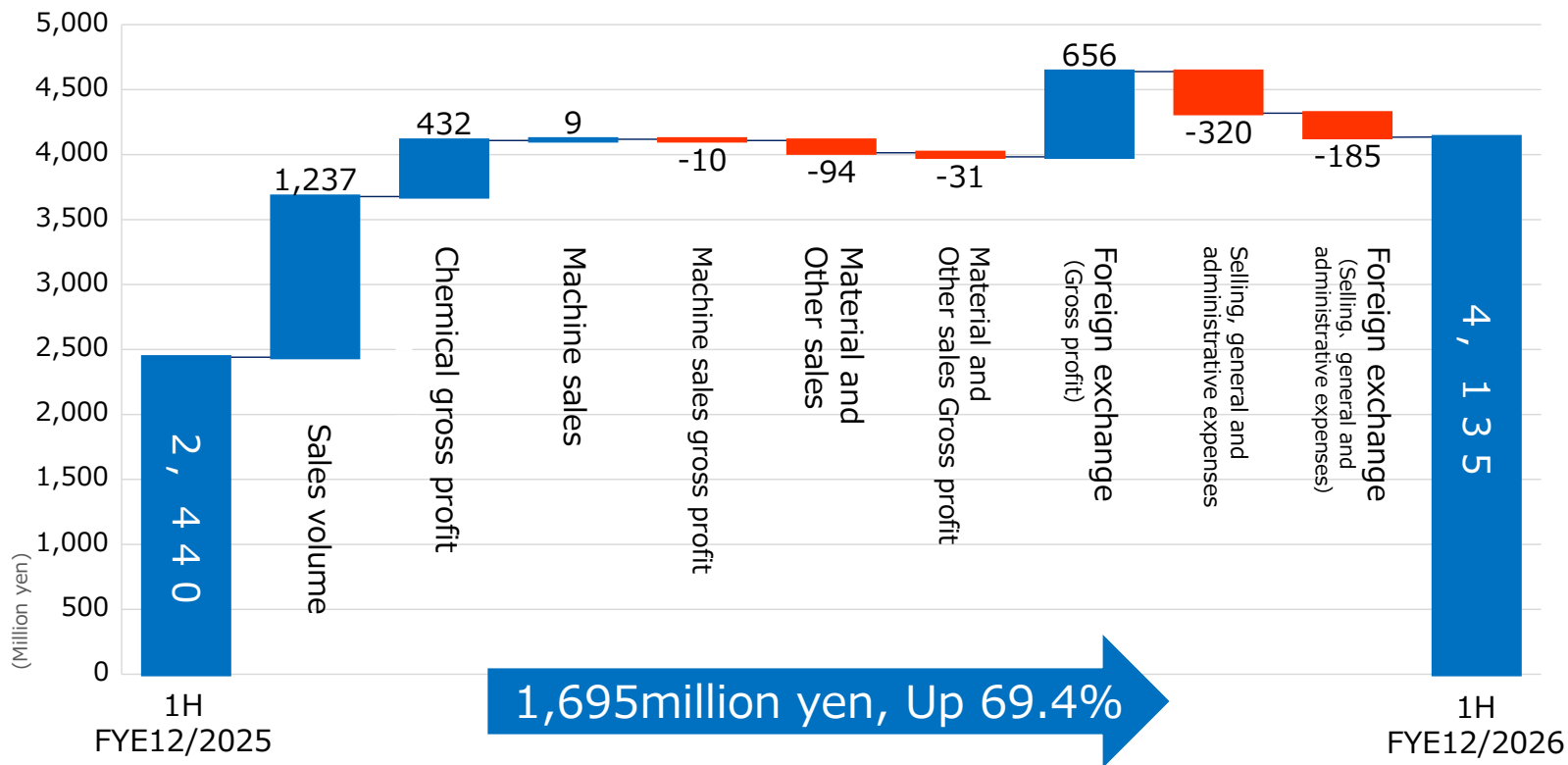
Unit : million yen

	1H						Full-year		
	FYE12.2025		FYE12.2026				FYE12.2025	FYE12.2026	
	Results	Progress ratio (%)	Results	Progress ratio (%)	YOY (%)		Results	(Forecast)	YOY (%)
Net sales	9,387	44.8%	12,594	48.8%	3,207	34.2%	20,947	25,800	23.2%
Chemical sales	9,025	-	12,402	-	3,376	37.4%	20,211	-	-
Gross profit	5,804	-	8,004	-	2,200	37.9%	12,977	-	-
Gross profit margin	61.8%	-	63.6%	-	-	-	62.0%	-	-
SGA	3,363	-	3,868	-	505	15.0%	7,229	-	-
Sales ratio	35.8%	-	30.7%	-	-	-	34.5%	-	-
Operating income	2,440	42.5%	4,135	49.8%	1,695	69.4%	5,748	8,300	44.4%
Operating profit margin	26.0%	-	32.8%	-	-	-	27.4%	32.2%	-
Ordinary income	2,493	41.2%	4,305	50.7%	1,811	72.6%	6,051	8,500	40.5%
Ordinary profit margin	26.6%	-	34.2%	-	-	-	28.9%	32.9%	-
Profit before tax	2,892	-	4,300	-	1,407	48.7%	6,473	-	-
Net income	1,893	37.7%	3,039	50.7%	1,145	60.5%	5,028	6,000	19.3%
EBITDA	3,287	-	4,731	-	1,444	43.9%	7,302	-	-
EPS	101.47	-	166.43	-	-	-	272.14	328.58	-
ROE	7.0%	-	9.1%	-	-	-	17.5%	17.5%	-

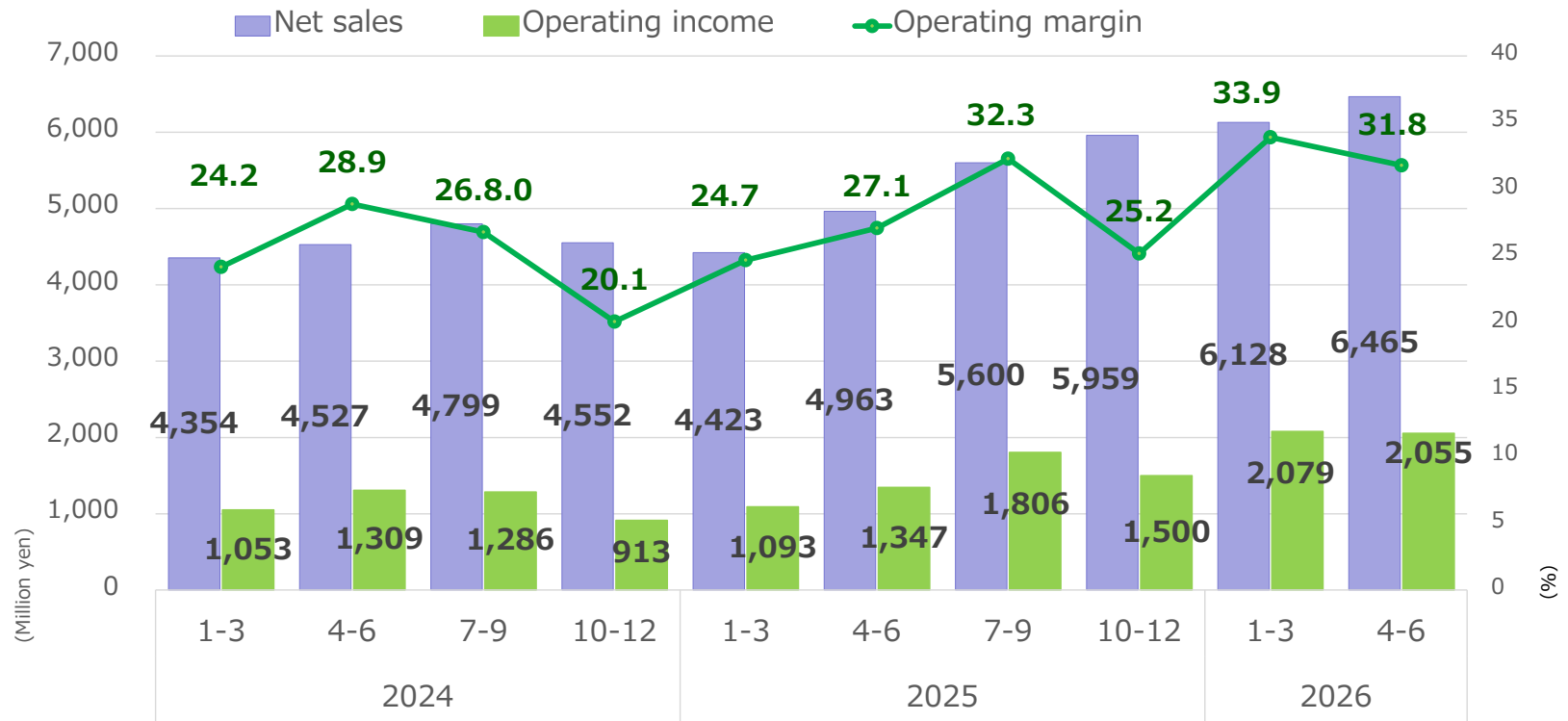
Net Sales YOY



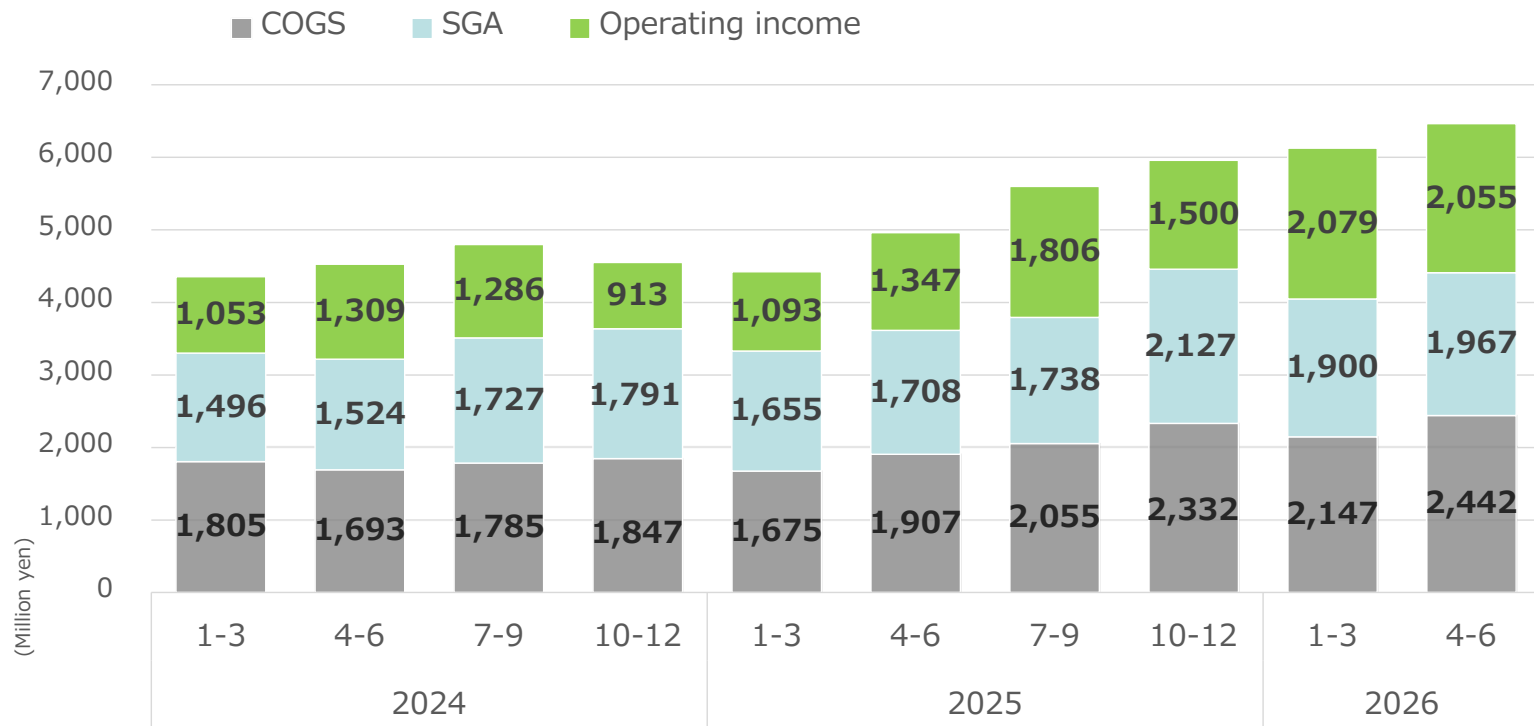
Operating Income YOY



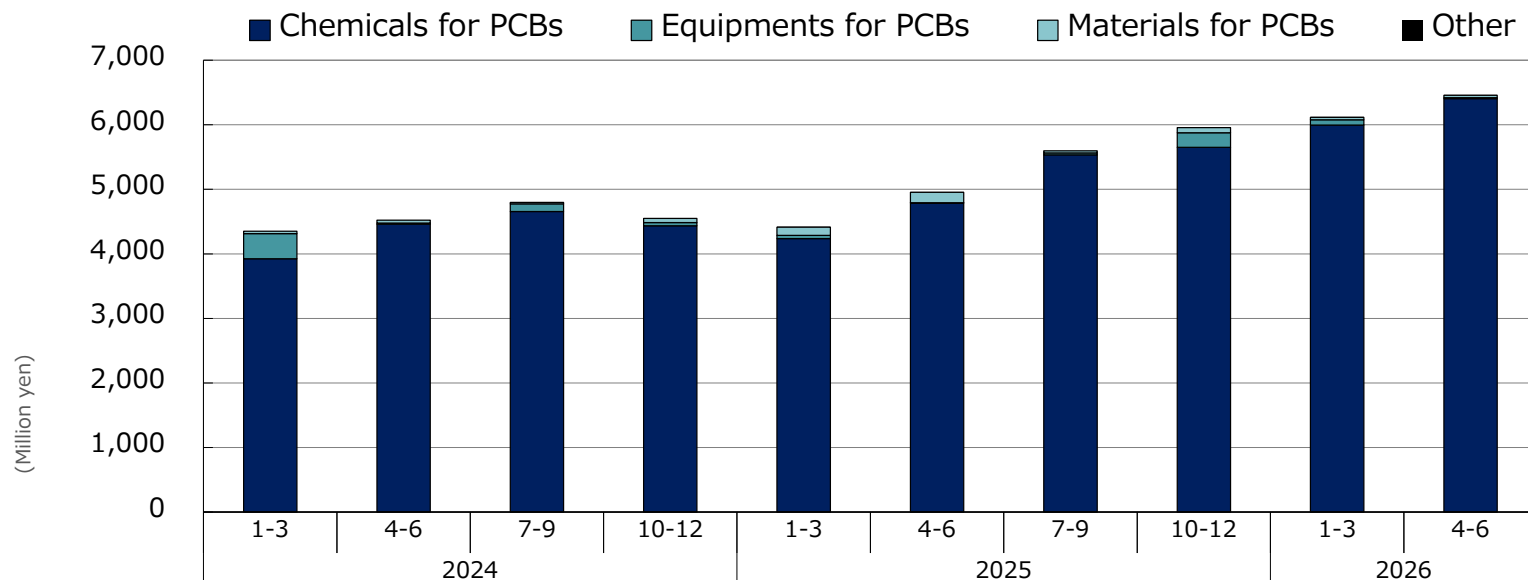
Quarterly Performance: Sales, Operating Income, Operating Margin (Consolidated)



Quarterly Composition: Operating Income, SG&A, CODS (Consolidated)

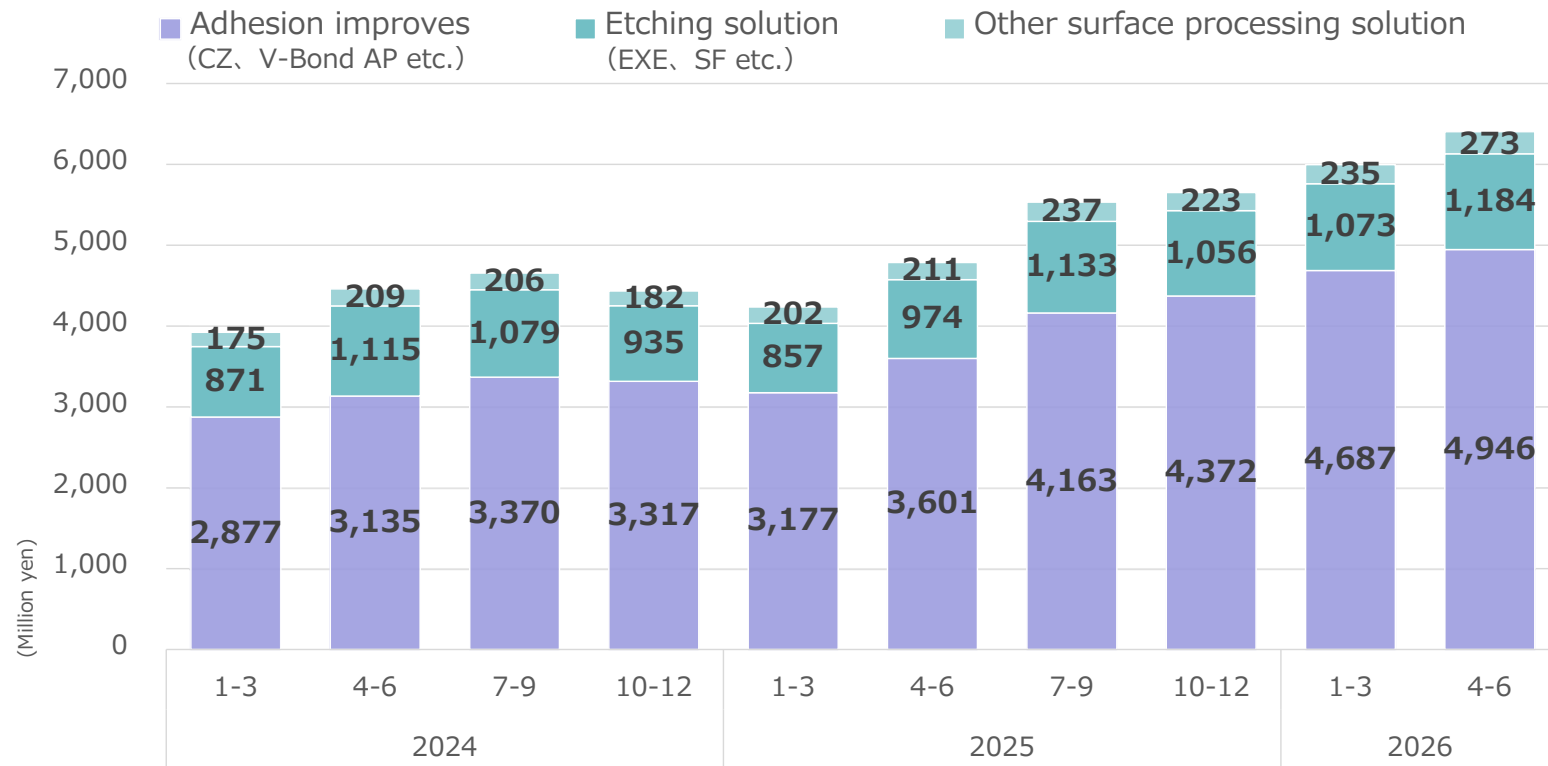


Quarterly Performance : Product-Specific Sales (Consolidated)

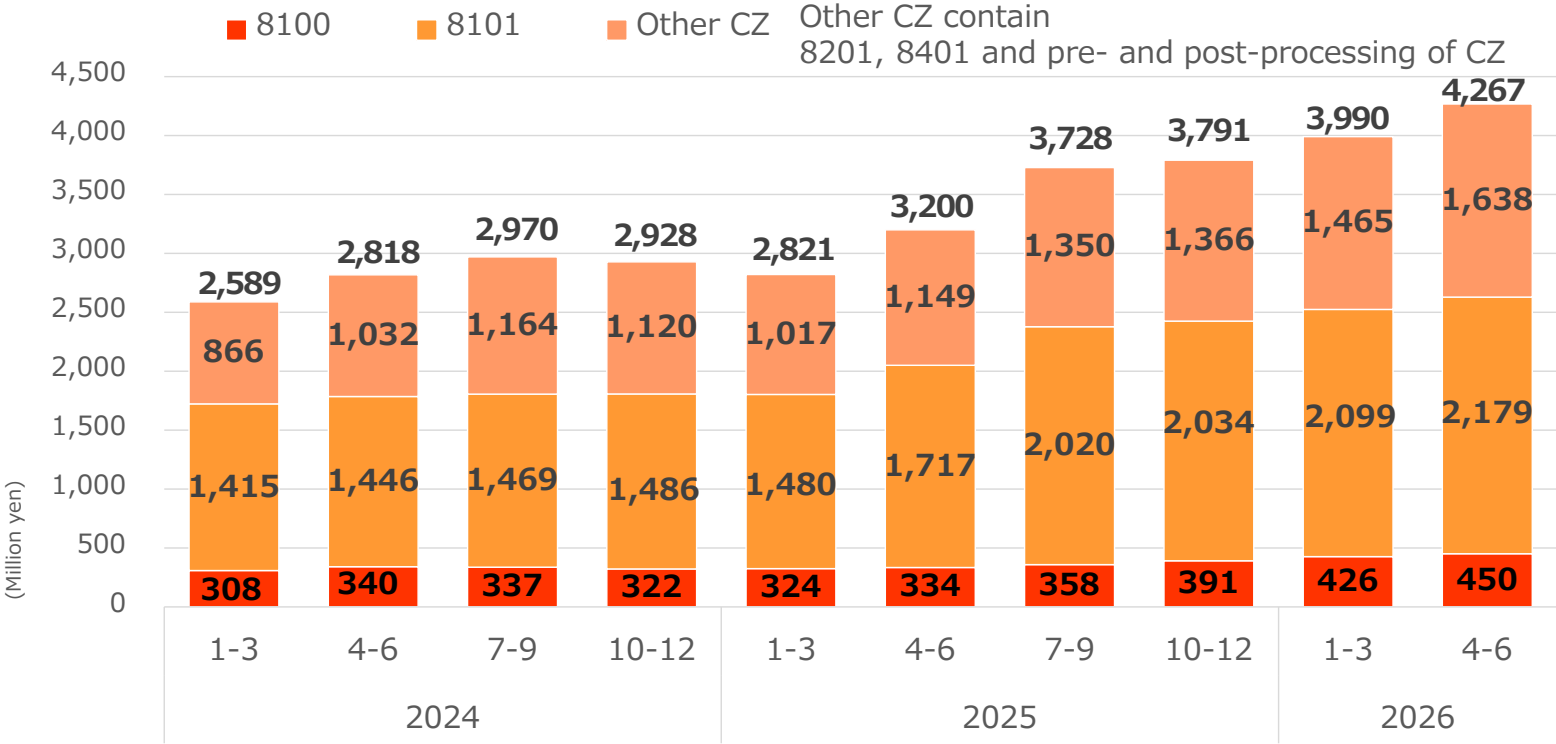


■ Other	1	3	1	1	8	7	2	1	10	6
■ Materials for PCBs	37	44	22	64	128	160	33	80	38	38
■ Equipments for PCBs	391	19	118	49	49	7	30	225	81	16
■ Chemicals for PCBs	3,924	4,460	4,657	4,436	4,237	4,787	5,534	5,652	5,997	6,404

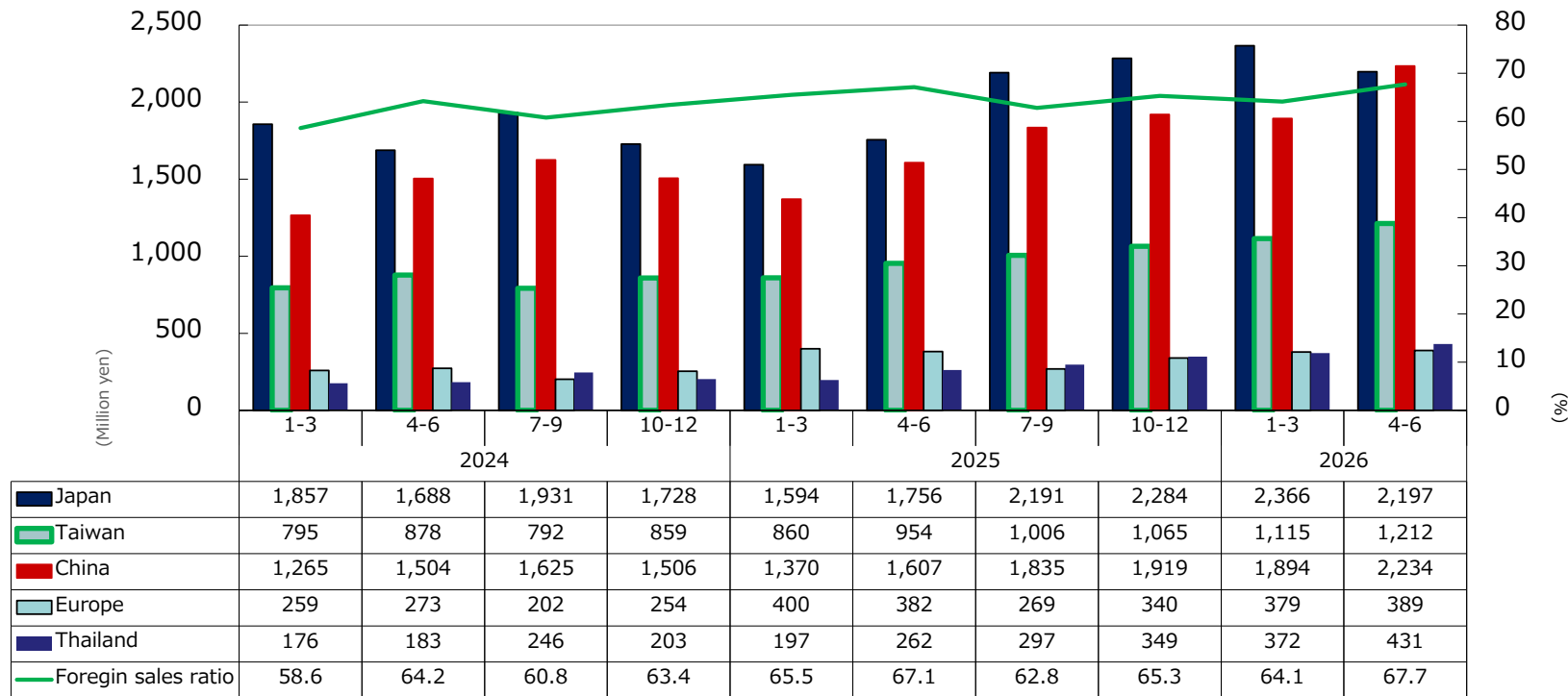
Quarterly Performance : Chemical Sales (Consolidated)



Quarterly Performance : CZ Series Sales



Quarterly Performance : Region-Specific Sales and Overseas Sales Ratio



Overseas sales ratio is 82.7%(same period of the previous year: 81.2%)
including sales to overseas customers through agents in Japan.

Our Future Plans

Our Future Plans

Business environment

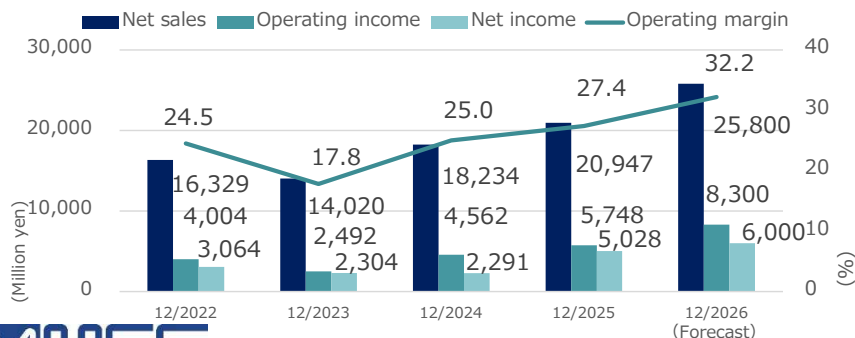
- In the medium to long term, technological innovation is expected to advance against the backdrop of the ongoing digital revolution and the spread of technologies such as IoT, AI, 5G/6G, electrification of vehicles, and the promotion of DX and GX, and markets related to our company are expected continue expanding.
- Demand for the related CZ series and chemical adhesion promoter is expected to increase, driven by ultra-high density, ultra-high frequency, and higher performance, as well as the rise in PKG substrates resulting from growing semiconductor demand.

Major chemical

- CZ : In the short term, demand will be affected by trends in the semiconductor market. In the medium to long term, demand is expected to expand due to an increase in PKG substrates and advances in larger and more multilayered designs.
- V-Bond Demand for satellite communication boards is on an upward trend.
Demand will be affected by trends in the automobile and smartphone market.
- EXE : Demand will be affected by trends in the display market. Due to the need for fine wiring formation, an increase in demand is expected in applications other than those for display market.
- SF : Demand will be affected by trends in the tablet PC market.

FYE12/2026 Full-year Forecast

	FYE12/2025		FYE12/2026 Revised: August 10, 2026		
	Full-year		Full-year		
	Amount (million yen)	Profit ratio (%)	Amount (million yen)	Profit ratio (%)	YOY change (%)
Net sales	20,947	-	25,800	-	23.2
Operating income	5,748	27.4	8,300	32.2	44.4
Ordinary income	6,051	28.9	8,500	32.9	40.5
Net income	5,028	24.0	6,000	23.3	19.3
Net income per share(yen)	272.14	-	328.58	-	-

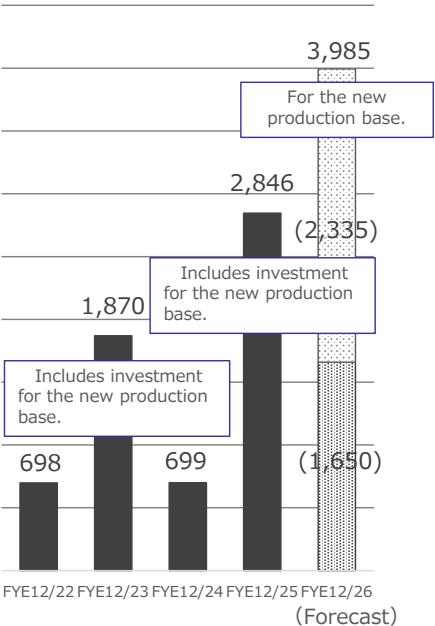


Exchange rates			FYE12/2025 Actual	FYE12/2026 Assumed
N	T	D	4.81	4.96
R	M	B	20.94	22.58
T	H	B	4.57	4.93
E	U	R	169.14	183.65
U	S	D	150.40	156.45

Capital Investment, Depreciation Expenses and R&D Expenses

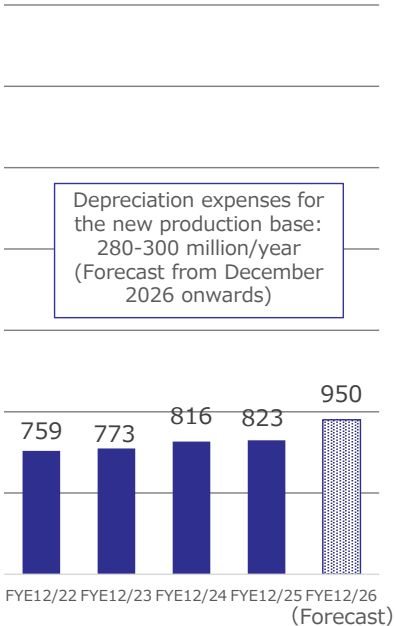
Capital investment

(million yen)



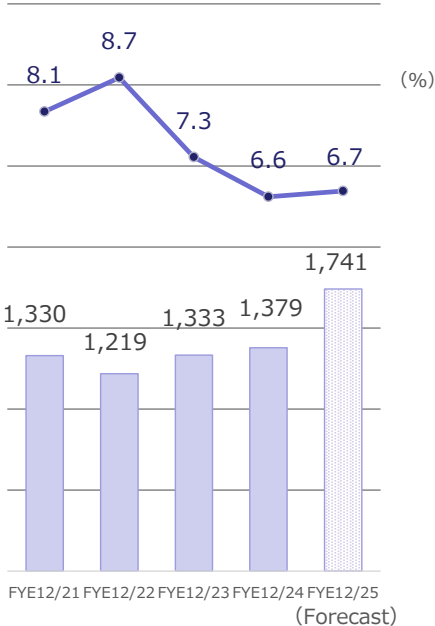
Depreciation expenses

(million yen)



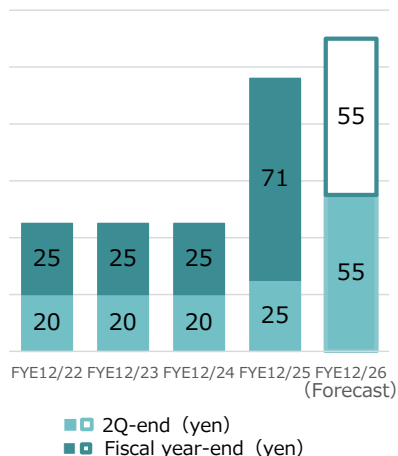
R&D expenses and Ratio of consolidated sales

(million yen)

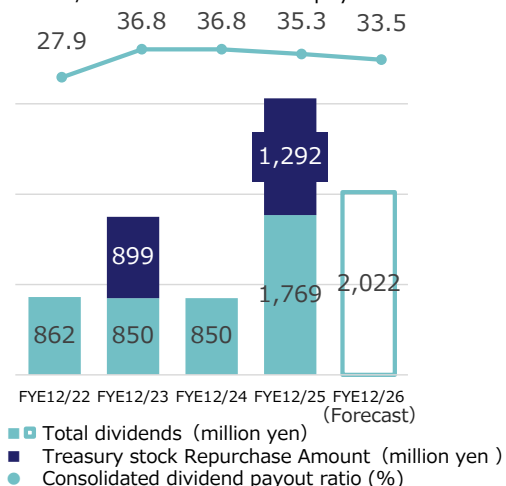


Trends in Total Dividends, Consolidated Dividend Payout Ratio, and ROE

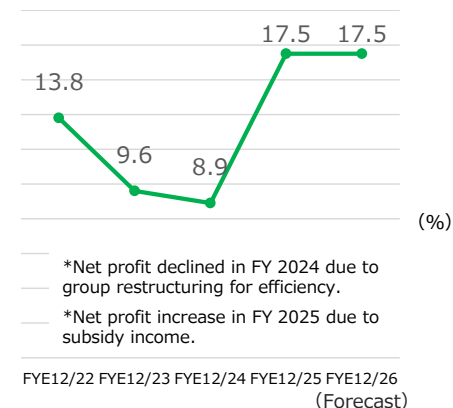
Dividends per share



Total dividends / Treasury stock repurchase amount/Consolidated dividend payout ratio



ROE



Shareholder Return Policy

- Consolidated dividend payout ratio: 35% or higher, and
- DOE (Dividend on Equity): 4.0% or higher
- Share repurchases to be conducted flexibly depending on circumstances

ROE

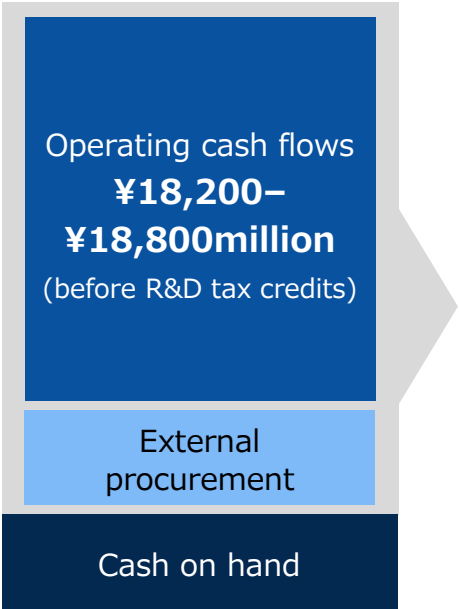
- 13% ~ 16%

Basic Policy on Cash Allocation

The basic policy on cash allocation for 2030 Vision: Phase 2 (cumulative for 2025–2027) is as follows.

*The size of each item is not an indicator of the amount.

Cash inflow/cash on hand (three-year total)



Cash outflow (three-year total)



Investment allocation	
• Capital investment for growth	¥4,000 million
• Investment for maintaining and renewing facilities	¥4,000 million
• Reinforcement of technical support and marketing structures	Amount to be determined as appropriate
• M&A	
• R&D	¥5,200 million
• Dividends	¥5,300–¥5,400 million
• Share buybacks	To be implemented flexibly
(Share buybacks of ¥1,292 million completed in 2025)	



Environment

- Development of products that reduce environmental impact.
- Appropriate chemical substance management.
- Promotion of resource recycling.
- Measures to address climate change.

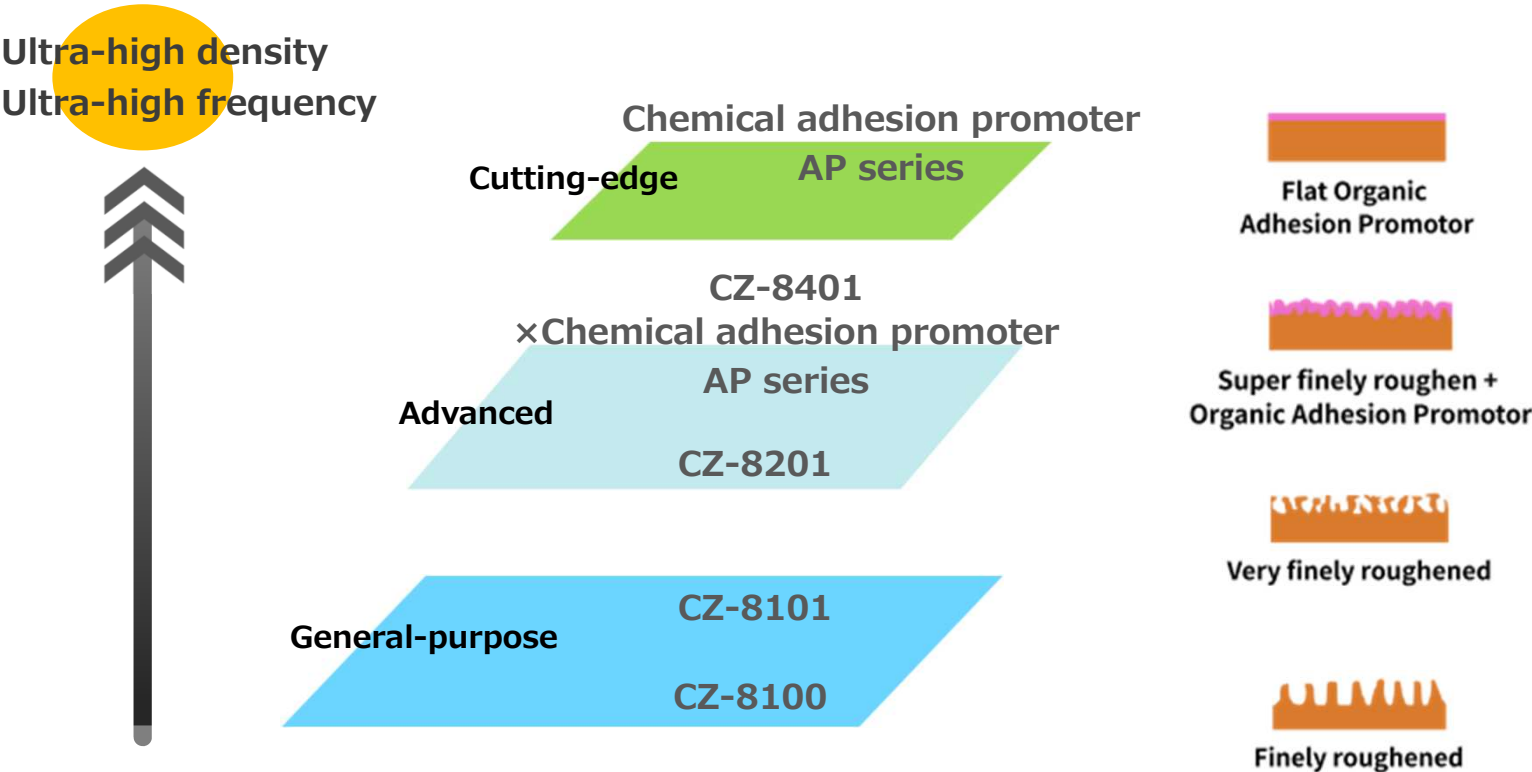
Social

- Human capital strategy.
- Utilization of diverse human resources (empowerment of women, WLB, promotion of men taking childcare leave, etc.).
- Contribution to social development (5G, autonomous driving).

Governance

- Reinforcement of management foundations (CG system, various committees, risk management, etc.).

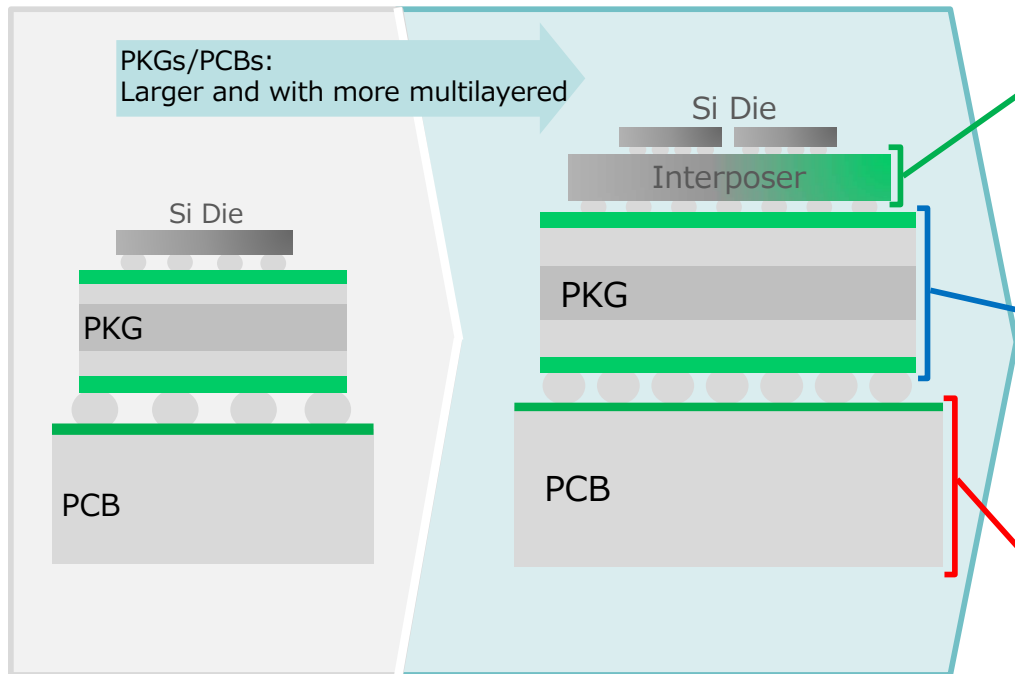
Our Products & PKG Substrate Trend



Aiming to Expand the Technical Domain

Evolution of Our Company's Technology and Required Technology

Ultra-high density, low signal loss, low power consumption



New field (Interposer)

- Products : Roughening adhesion(CZ)×Chemical adhesion(AP)
- Technical trend : Ultra-high density (Low L/S)
- Final products : Generative AI、Data centers

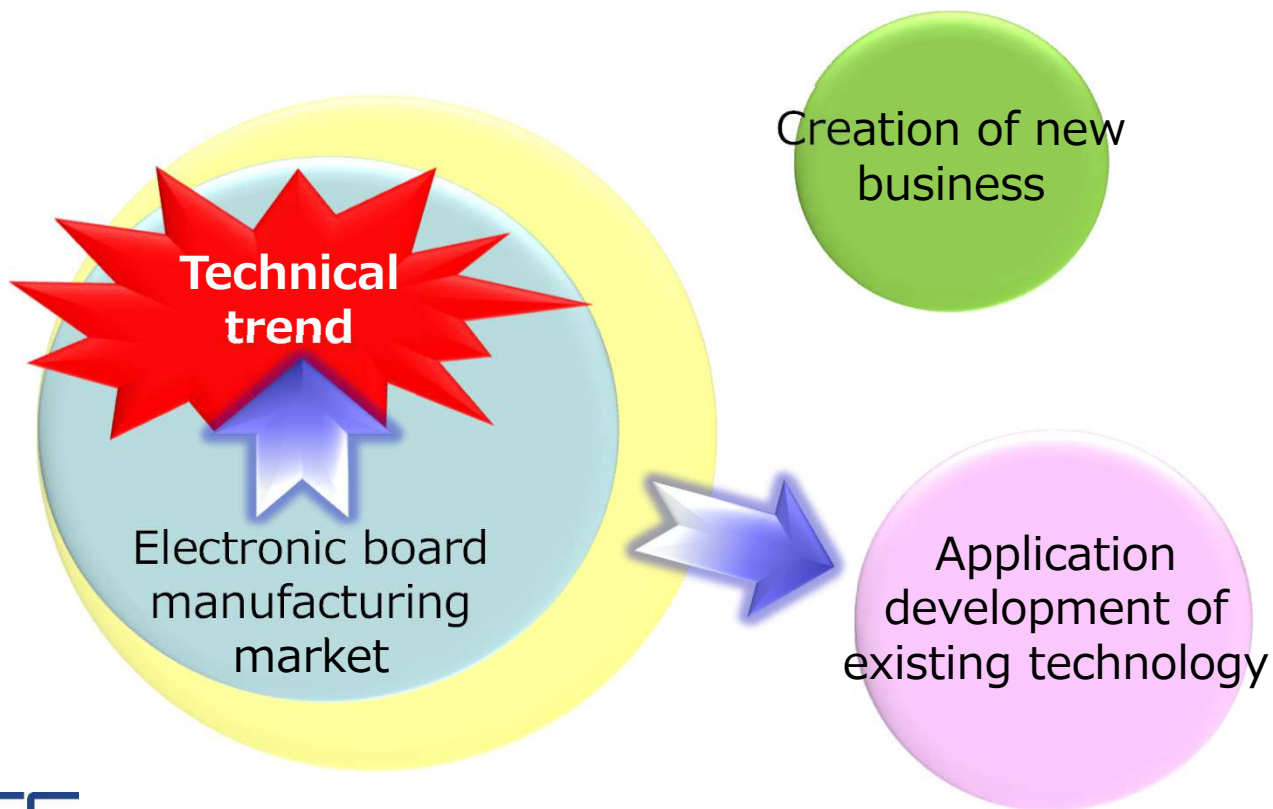
Existing field (PKG)

- Products : Roughening adhesion(CZ), Chemical adhesion(AP)
- Technical trend : High density (Low L/S)
Reduction of coarsening amount due to low Power consumption needs
- Final products : Generative AI、Data centers

New field (High-frequency)

- Products : Chemical adhesion(AP)
- Technical trend : Reduction of roughening amount due to low signal loss requirements
- Final products : Generative AI, Data centers, Semiconductor inspection equipment

Aiming to Expand the Business Domain



Appendix

Corporate Profile

(As of December 31, 2025)

Company name	MEC COMPANY LTD.
Head quarters location	3-4-1, Kuise Minamishimmachi, Amagasaki, Hyogo
Date of establishment	May 1, 1969
Business activities	R&D, production and sales of chemicals, equipment and related materials used in the production of PCBs and electronic components.
Presentative	President and CEO Kazuo Maeda
Capital	594,142,400 JPY
Net sales	20,947 million JPY (Consolidated)
Stock listing	Tokyo Stock Exchange Prime Market, Securities code: 4971
Number of employees	508 persons (Consolidated), 292 persons (Non-consolidated)

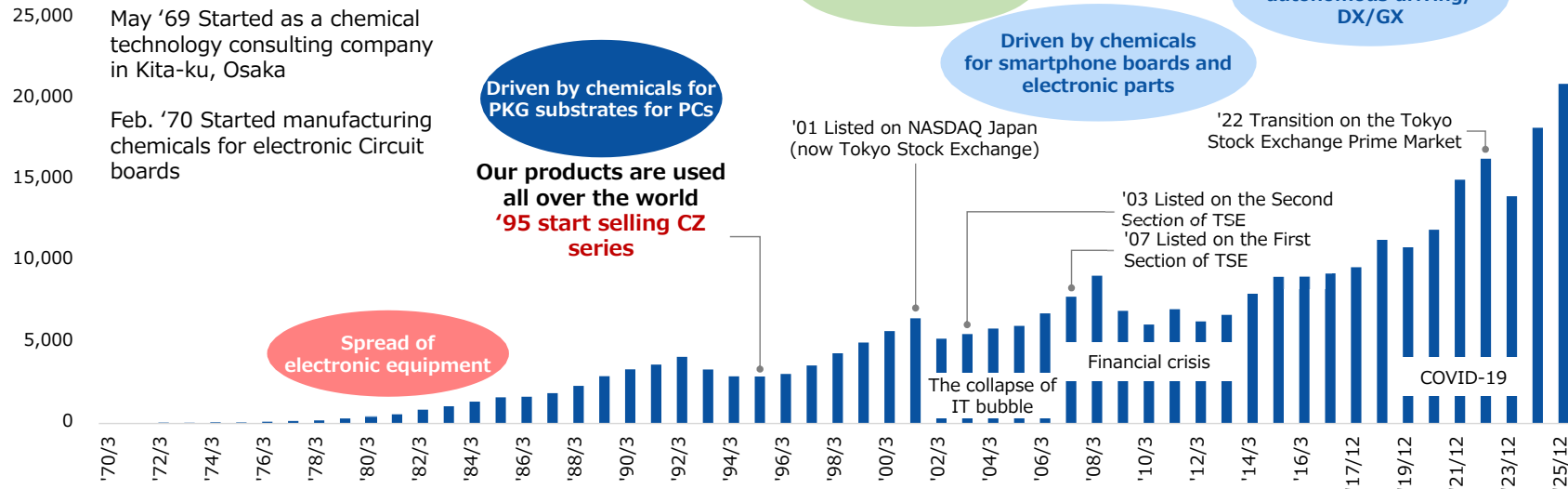
MEC Sales Trend Since Foundation

Electronic circuit boards mainly used for personal devices

Uses of electronic circuit boards expanded to social infrastructure

Net sales

(Million yen)



*FYE 12/2017 is a period of nine months from April 1 to December 31 of 2017 due to the change of the accounting period. The consolidated period for MEC is a period of nine months (from April 1 to December 31 of 2017) while that for consolidated subsidiaries is a period of twelve months (from January 1 to December 31 of 2017).



Process of Commercialization



From R&D
To Factory



Beaker experiment ⇒ Scale-up experiment ⇒ Production line verification



Manufacturing ⇒ Quality inspection ⇒ Filling

To
customers



Example of Product Usage Process

«Drying»



«Water rinse»



«Chemical treatment»



MEC's Core Technologies

Creating and Fostering Value at Various Interfaces

- **Roughen** the surface, and
physically improve adhesion
CZ,V-Bond
- **Pattern formation**
EXE
- **Selective etching**
SF
- **Treat** the surface, and
chemically adhesion promoter
AP

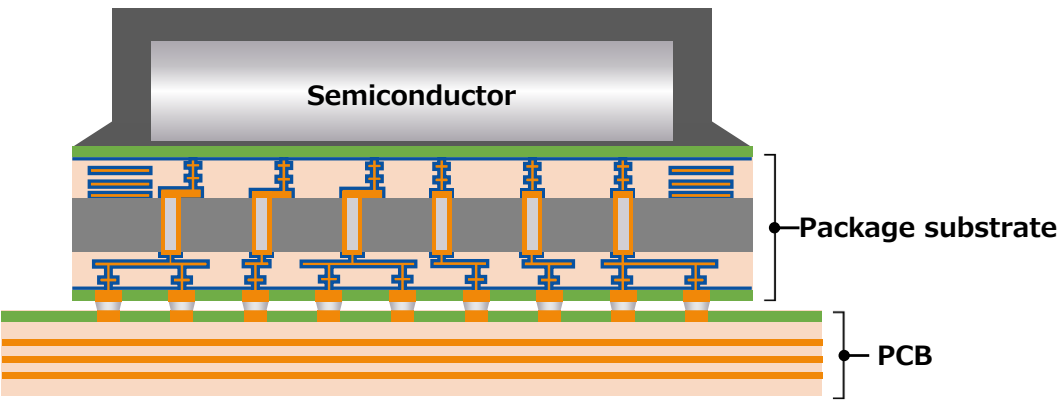


Examples of Major Chemical Applications and Final Products

Major chemical	Characteristic	Final products
Super-roughening type adhesive enhancement CZ series	A copper surface treatment agent that enhances adhesion between copper and resin. It is mainly an adhesion improver for PKG substrates, and is also used for high-density PCBs.	Infrastructure (Generative AI, 5G/6G-related, data centers, etc.) and high-function devices (PCs, smartphones, tablet PCs, etc.)
Adhesion improvers for multilayer substrates V-Bond series	A copper surface treatment agent that enhances adhesion between copper and resin. Adhesion improver mainly for multilayer substrates. Not used for PKG substrates.	Automobile, smartphones, Satellite communications etc.
Anisotropic etchant EXE series	Fine wiring can be formed through subtraction. Etching agent for COF substrates.	TV and PC monitors, etc.
Selective etchant SF series	Etching agent with selectivity to copper.	Tablet PCs, etc.

Our Strength: Interlayer Adhesion Technology

The CZ series, our main products, is used as an adhesion promoter in the parts where copper contacts with resin. It is an indispensable technology in the process of improving adhesion between the copper and the build-up resin of package substrates.



- Places where the CZ series is used
- Copper
- Solder masks
- Resin

As package substrates become larger and adopt more layers

⇒ **The amount of CZ series used increases**



Under development

0.0μm

(Chemical adhesion)

Flat organic adhesion promoter

CZ-8401 + series

(0.1μm + Chemical adhesion)

Super finely roughen + Organic adhesion promoter

CZ-8201 0.5μm

Very finely roughened

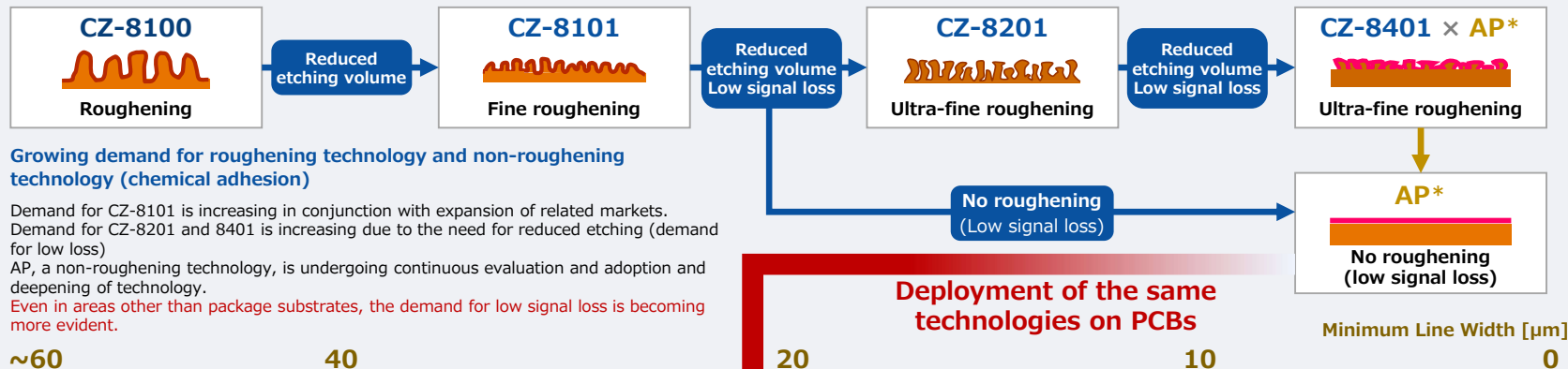
CZ-8101 1.0μm

Finely roughened

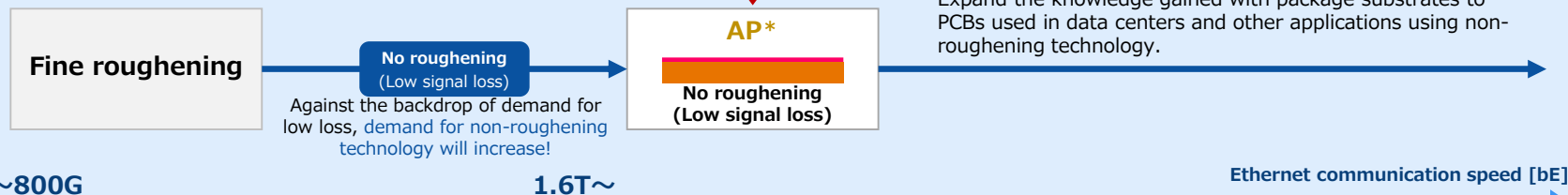
Reduced etching volume

Changes in Copper Adhesion Surface Technology

Core Business: Package substrates

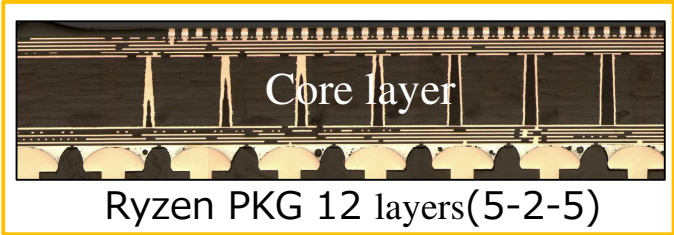
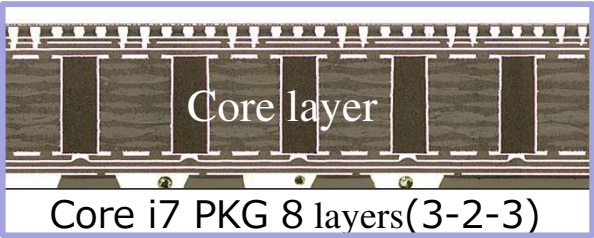
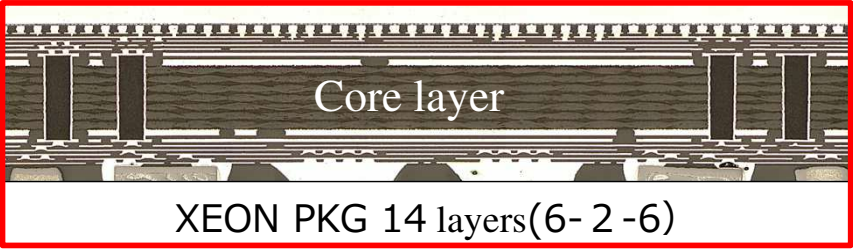


Application and Expansion: PCBs (High-frequency substrates)



* AP : Adhesion Promotor (Chemical adhesion using non-roughening technologies, chemical adhesion enhancement against fine roughening)

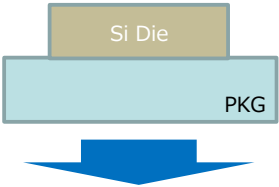
Cross Section Observations



	Size(cm ²)	Layers
XEON	27.44	14
Core i7	14.44	8
Ryzen 7	16.00	12

Evolution of the PKG Substrate

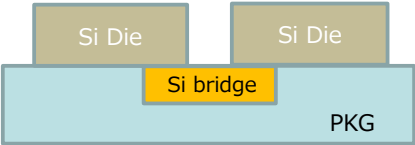
Conventional PKG substrate
One PKG, One Si Die



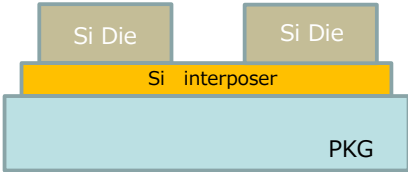
Advanced PKG substrate (Chiplet, 2.X/3D)
Enlarging PKG to mount multiple semiconductors

- High-density PKG
- Large-size PKG
- High multi-layer PKG

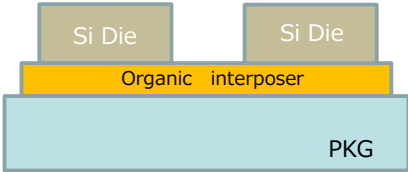
EMIB/EMIB-T
(Embedded **M**ulti-die **I**nterconnect **B**ridge)



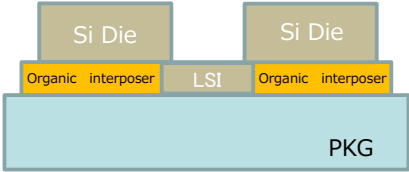
CoWoS-S
(Chip on **W**afer on **S**ubstrate)



CoWoS-R
(Chip on **W**afer on **S**ubstrate)



CoWoS-L
(Chip on **W**afer on **S**ubstrate)



MEC Group Equipment Capacity

Domestic base (Japan)



Amagasaki Factory
900 t / mo.



Nagaoka Factory
2,750 t / mo.

New production base
(Under construction)



Kitakyushu Plant Maximum capacity
2,500 t /mo. (Plan)

Global base



MEC TAIWAN
1,200 t / mo.



MEC SUZHOU
1,350 t / mo.



MEC ZHUHAI
1,000 t / mo.



MEC EUROPE
400 t / mo.



MEC THAILAND
500 t / mo.

Creating and Fostering Value at Various Interfaces



This presentation includes forward-looking statements (such as predictions and business forecasts) made on August 10, 2026. These statements are assumptions based on information available at the time, and they are subject to risks and uncertainties. Actual results or events could differ substantially from those forecasted in such statements due to a variety of factors.